Operational Amplifier

Automotive Low Offset Low Noise & Rail-to-Rail Input/Output High Speed CMOS Operational Amplifier

TLR728YG-C TLR2728YFJ-C

General Description

These products are Rail-to-Rail input/output monolithic IC integrated single or dual independent CMOS operational amplifiers. It features low offset, high slew rate, low noise and low input bias current. It is suitable for automotive requirements such as engine control unit, electric power steering, anti-lock braking system, sensor amplifier, and so on.

Features

- Nano Cap™ Integrated OPAMP
- AEC-Q100 Qualified*(Note 1)*
- Functional Safety Supportive Automotive Products
- Low Input-Referred Noise Voltage Density
- Rail-to-Rail Input/Output

(Note 1) Grade 1

Applications

- Engine Control Unit
- Electric Power Steering (EPS)
- Anti-lock Braking System (ABS)
- Automotive Electronics
- Sensor Amplifiers
- Battery-powered Equipment
- Current Monitoring Amplifier
- ADC Front Ends, Buffer Amplifier
- Photodiode Amplifiers
- Amplifiers

Key Specifications

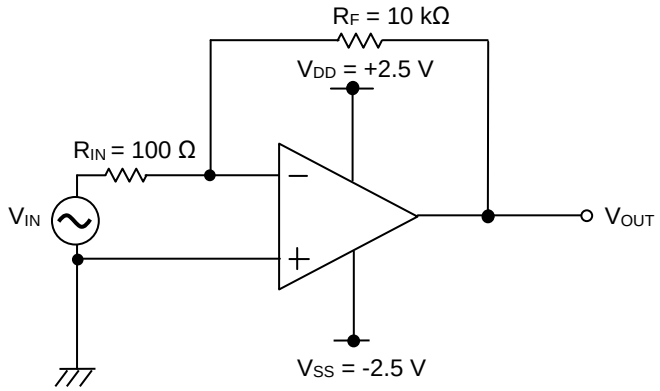
- Input Offset Voltage: 550 µV (Max)
- Slew Rate: 10 V/µs (Typ)
- Input-Referred Noise Voltage Density
  f = 1 kHz: 12 nV/√Hz (Typ)
- Common-mode Input Voltage Range: V_{SS} to V_{DD}
- Input Bias Current: 0.5 pA (Typ)
- Operating Supply Voltage Range
  Single Supply: 2.5 V to 5.5 V
  Dual Supply: ±1.25 V to ±2.75 V
- Operating Temperature Range: -40 °C to +125 °C

Package	W (Typ) x D (Typ) x H (Max)
SSOP5	2.9 mm x 2.8 mm x 1.25 mm
SOP-J8	4.9 mm x 6.0 mm x 1.65 mm

SSOP5
reference code: SOT23-5

SOP-J8
reference code: SOIC-8

Typical Application Circuit



$$V_{OUT} = -\frac{R_F}{R_{IN}} V_{IN}$$

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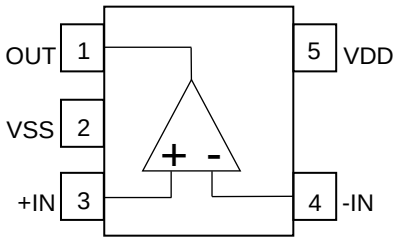
Pin Configuration

TLR728YG-C (SSOP5)

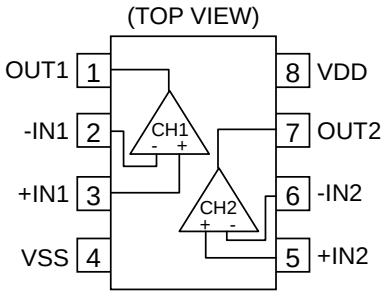
(TOP VIEW)



Pin No.	Pin Name	Function
1	OUT	Output
2	VSS	Negative power supply / Ground
3	+IN	Non-inverting input
4	-IN	Inverting input
5	VDD	Positive power supply

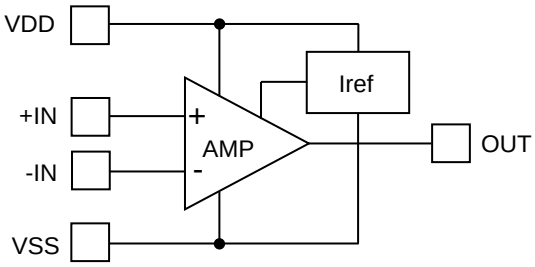
TLR2728YFJ-C (SOP-J8)

(TOP VIEW)



Pin No.	Pin Name	Function
1	OUT1	Output1
2	-IN1	Inverting input1
3	+IN1	Non-inverting input1
4	VSS	Negative power supply / Ground
5	+IN2	Non-inverting input2
6	-IN2	Inverting input2
7	OUT2	Output2
8	VDD	Positive power supply

Block Diagram



(Note) Each channel has the same configuration.

Description of Blocks

1. AMP:
   This block is a full-swing output operational amplifier with class-AB output circuit and high-precision-Rail-to-Rail differential input stage.

2. Iref:
   This block supplies reference current which is needed to operate AMP block.

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Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage (V_{DD} - V_{SS})	V_S	7.0	V
Input Pin Voltage (+IN, -IN)	V_I	(V_{SS} - 0.3) to (V_{SS} + 7.0)	V
Input Pin Current (+IN, -IN)	I_I	10	mA
Maximum Junction Temperature	Tjmax	150	°C
Storage Temperature Range	Tstg	-55 to +150	°C

Caution 1: *Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.*

Caution 2: *Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.*

Thermal Resistance*(Note 1)*

Parameter	Symbol	Thermal Resistance (Typ)		Unit
		1s*(Note 3)*	2s2p*(Note 4)*	
SSOP5				
Junction to Ambient	θ_{JA}	376.5	185.4	°C/W
Junction to Top Characterization Parameter*(Note 2)*	Ψ_{JT}	40	30	°C/W
SOP-J8				
Junction to Ambient	θ_{JA}	149.3	76.9	°C/W
Junction to Top Characterization Parameter*(Note 2)*	Ψ_{JT}	18	11	°C/W

(Note 1) Based on JESD51-2A(Still-Air).
(Note 2) The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.
(Note 3) Using a PCB board based on JESD51-3.
(Note 4) Using a PCB board based on JESD51-7.

Layer Number of Measurement Board	Material	Board Size
Single	FR-4	114.3 mm x 76.2 mm x 1.57 mmt

Top	
Copper Pattern	Thickness
Footprints and Traces	70 µm

Layer Number of Measurement Board	Material	Board Size
4 Layers	FR-4	114.3 mm x 76.2 mm x 1.6 mmt

Top		2 Internal Layers		Bottom	
Copper Pattern	Thickness	Copper Pattern	Thickness	Copper Pattern	Thickness
Footprints and Traces	70 µm	74.2 mm x 74.2 mm	35 µm	74.2 mm x 74.2 mm	70 µm

Recommended Operating Conditions

Parameter		Symbol	Min	Typ	Max	Unit
Supply Voltage (V_{DD} - V_{SS})	Single Supply	V_S	2.5	5.0	5.5	V
	Dual Supply		±1.25	±2.50	±2.75	
Operating Temperature		Topr	-40	+25	+125	°C

Function Explanation

1. Nano Cap™
   Nano Cap™ is a combination of technologies which allow stable operation even if output capacitance is connected with the range of nF unit.

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Electrical Characteristics

(Unless otherwise specified V_S = 5 V, V_{SS} = 0 V, V_{ICM} = 2.5 V, R_L = 10 kΩ to V_{ICM}, Ta = 25 °C)

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Input Offset Voltage	V_{IO}	-	0.01	150	μV	No load, Absolute value
		-	-	550		No load, Absolute value, Ta = -40 °C to +125 °C
Input Offset Voltage Temperature Drift	$\Delta V_{IO}/\Delta T$	-5	+0.7	+5	μV/°C	No load, Ta = -40 °C to +125 °C
Input Offset Current	I_{IO}	-	0	-	pA	Absolute value
Input Bias Current	I_B	-	0.5	-	pA	Absolute value
Common-mode Input Voltage Range	V_{ICMR}	0	-	5	V	V_{SS} to V_{DD}
Supply Current	I_{DD}	-	1.7	2.6	mA/ch	No load, G = 0 dB
		-	-	2.8		No load, G = 0 dB, Ta = -40 °C to +125 °C
Output Voltage High	V_{OH}	-	20	100	mV	$V_{OH} = V_{DD} - V_{OUT}$ I_L = 1 mA
		-	-	150		$V_{OH} = V_{DD} - V_{OUT}$ I_L = 1 mA Ta = -40 °C to +125 °C
Output Voltage Low	V_{OL}	-	15	100	mV	I_L = 1 mA
		-	-	150		I_L = 1 mA Ta = -40 °C to +125 °C
Output Source Current *(Note 1)*	I_{OH}	25	50	-	mA	$V_{OUT} = V_{SS}$, Absolute value
Output Sink Current *(Note 1)*	I_{OL}	25	50	-	mA	$V_{OUT} = V_{DD}$, Absolute value
Large Signal Voltage Gain	A_V	95	115	-	dB	-
		75	-	-		Ta = -40 °C to +125 °C
Gain Bandwidth Product	GBW	-	7	-	MHz	G = 40 dB, C_L = 25 pF
Phase Margin	θ	-	65	-	deg	G = 40 dB, C_L = 25 pF
Common-mode Rejection Ratio	CMRR	65	100	-	dB	-
Power Supply Rejection Ratio	PSRR	65	100	-	dB	-
Slew Rate	SR	-	10	-	V/μs	C_L = 100 pF
		5	-	-		C_L = 100 pF, Ta = -40 °C to +125 °C
Input-Referred Noise Voltage Density	Vn	-	12	-	nV/√Hz	f = 1 kHz
Total Harmonic Distortion + Noise	THD+N	-	0.001	-	%	V_{OUT} = 4 Vp-p, f = 1 kHz
Channel Separation	CS	-	100	-	dB	Input Conversion

(Note 1) Consider the power dissipation of the IC under high temperature environment when selecting the output current value. When the output pin is short-circuited continuously, the output current may decrease due to the temperature rise by the heat generation of inside the IC.

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Typical Performance Curves
V_{SS} = 0 V

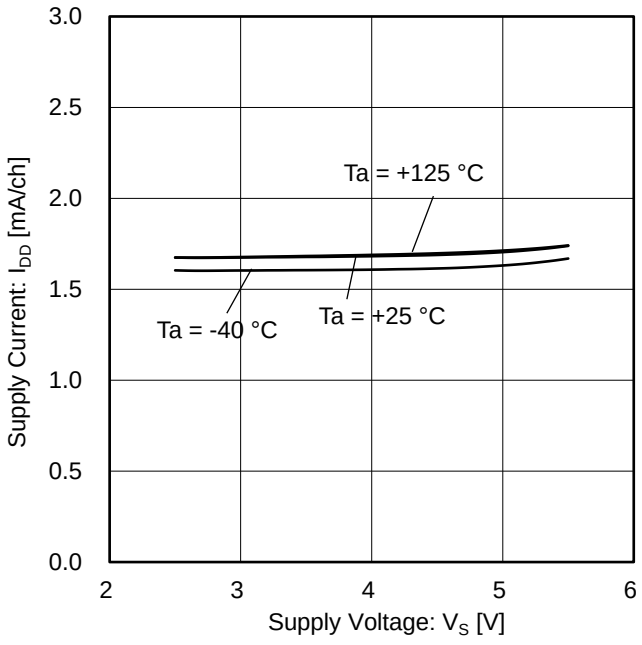

Figure 1. Supply Current vs Supply Voltage

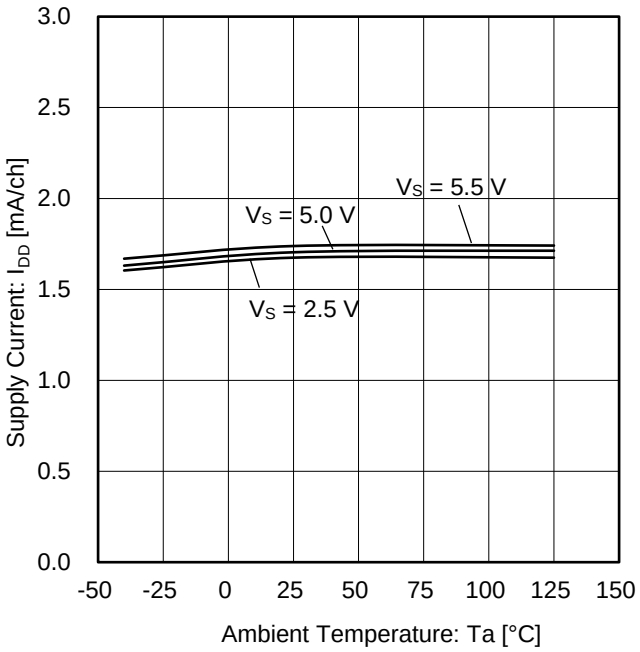

Figure 2. Supply Current vs Ambient Temperature

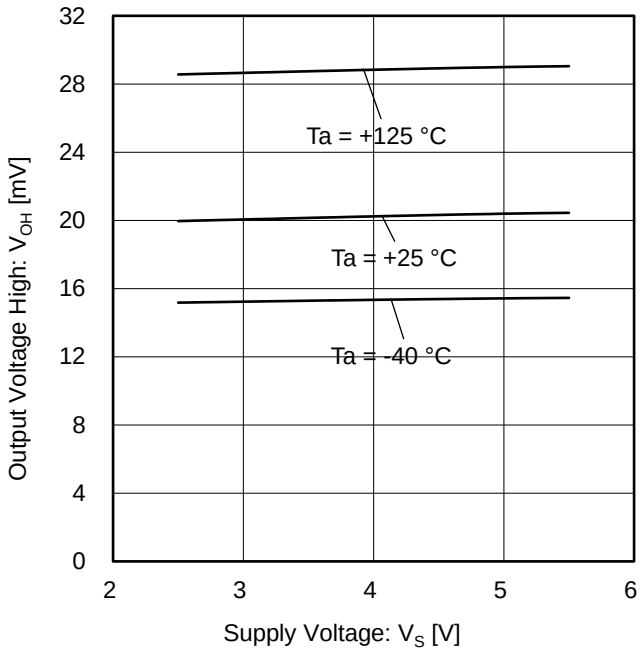

Figure 3. Output Voltage High vs Supply Voltage
(I_L = 1 mA)

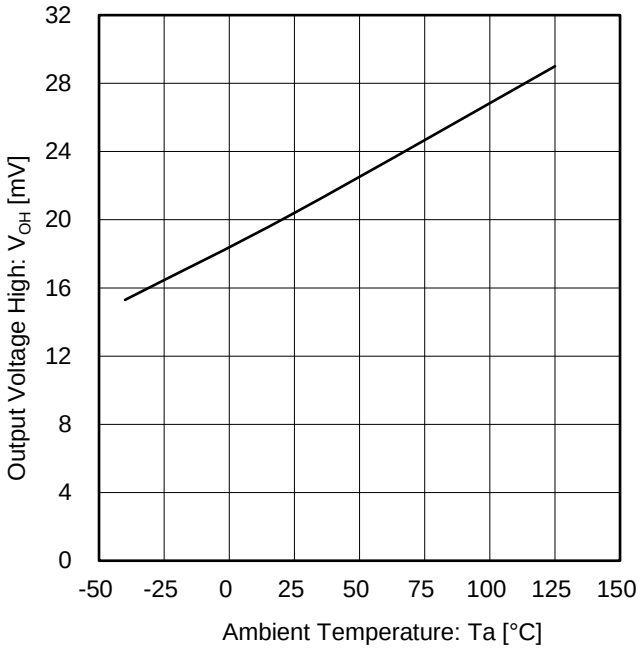

Figure 4. Output Voltage High vs Ambient Temperature
(V_S = 5 V, I_L = 1 mA)

(Note) The above data is measurement value of typical sample, it is not guaranteed.

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Typical Performance Curves - continued
V_{SS} = 0 V

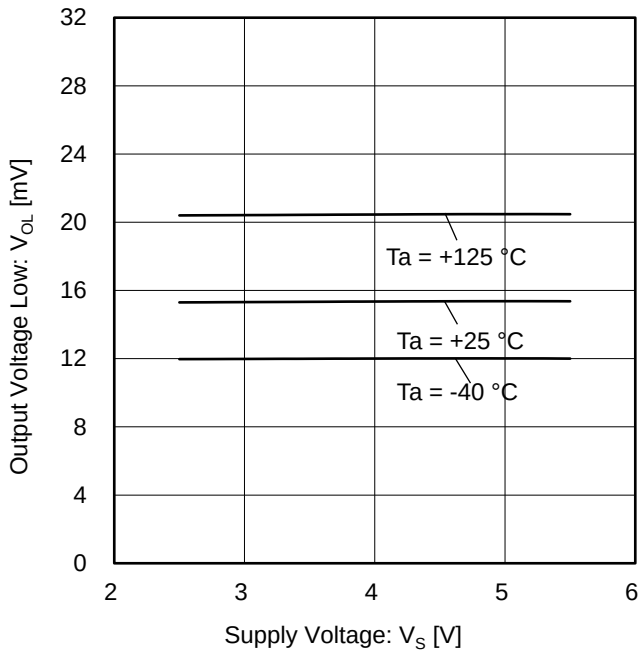

Figure 5. Output Voltage Low vs Supply Voltage
(I_L = 1 mA)

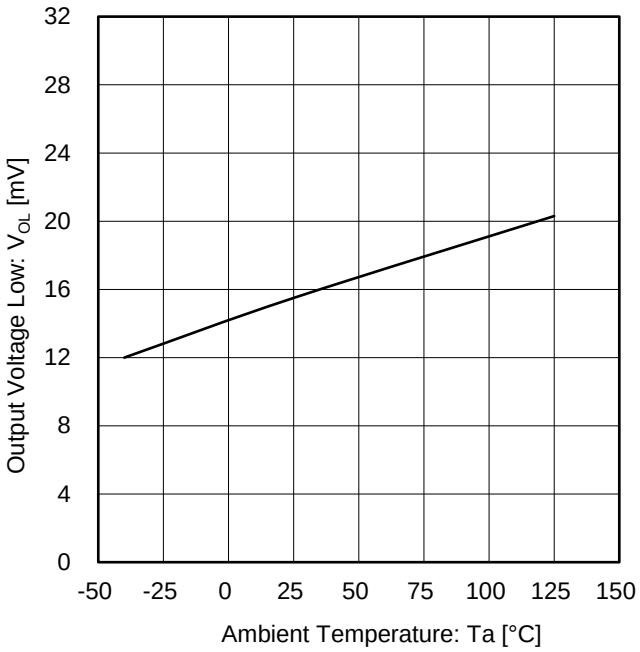

Figure 6. Output Voltage Low vs Ambient Temperature
(V_S = 5 V, I_L = 1 mA)

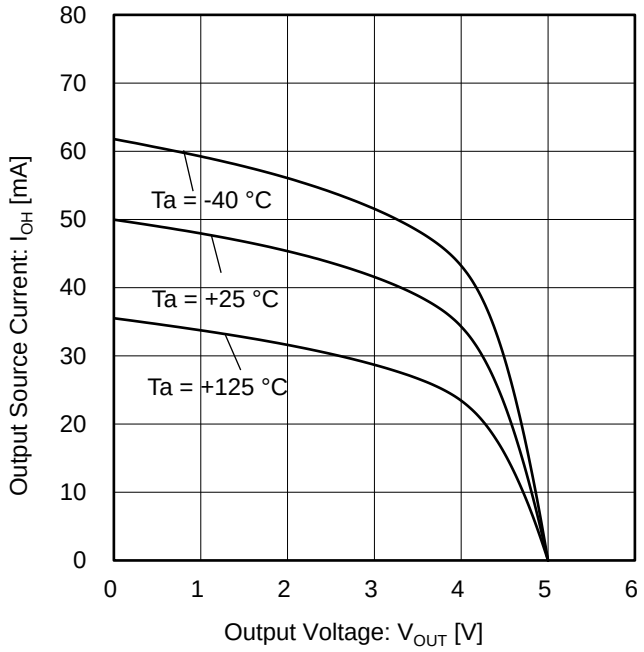

Figure 7. Output Source Current vs Output Voltage
(V_S = 5 V)

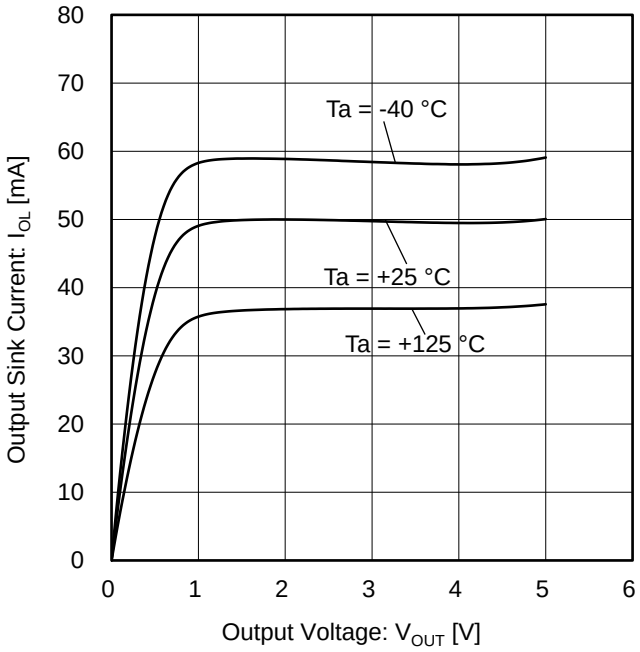

Figure 8. Output Sink Current vs Output Voltage
(V_S = 5 V)

(Note) The above data is measurement value of typical sample, it is not guaranteed.

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Typical Performance Curves - continued
V_{SS} = 0 V

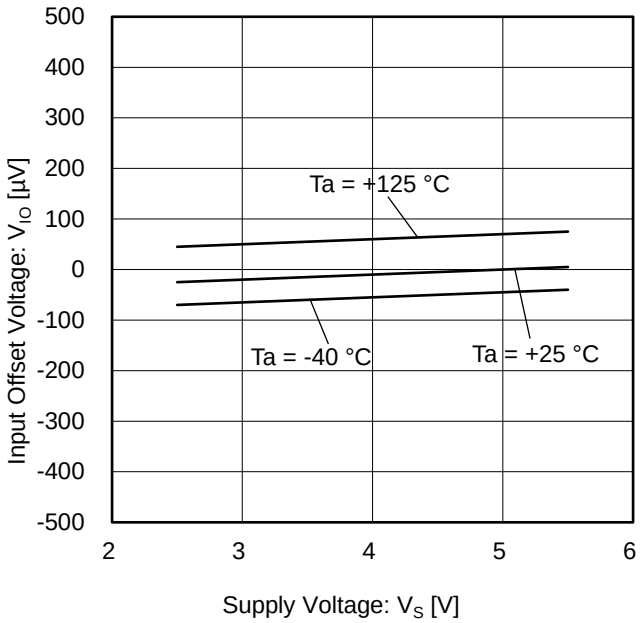

Figure 9. Input Offset Voltage vs Supply Voltage

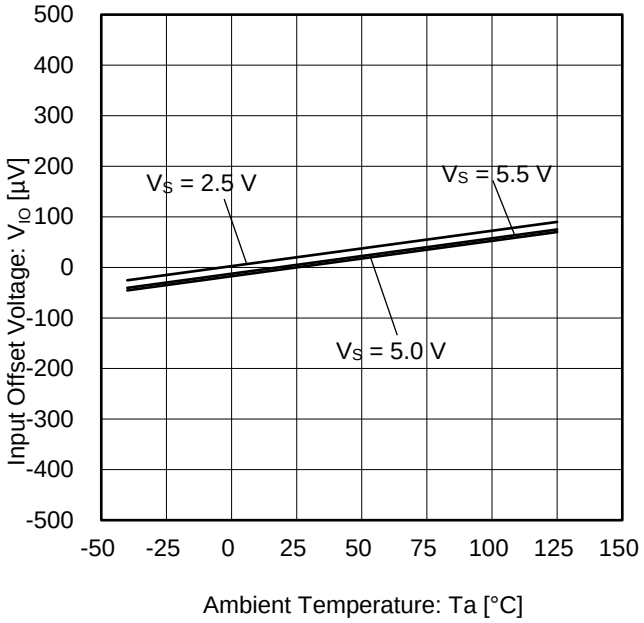

Figure 10. Input Offset Voltage vs Ambient Temperature

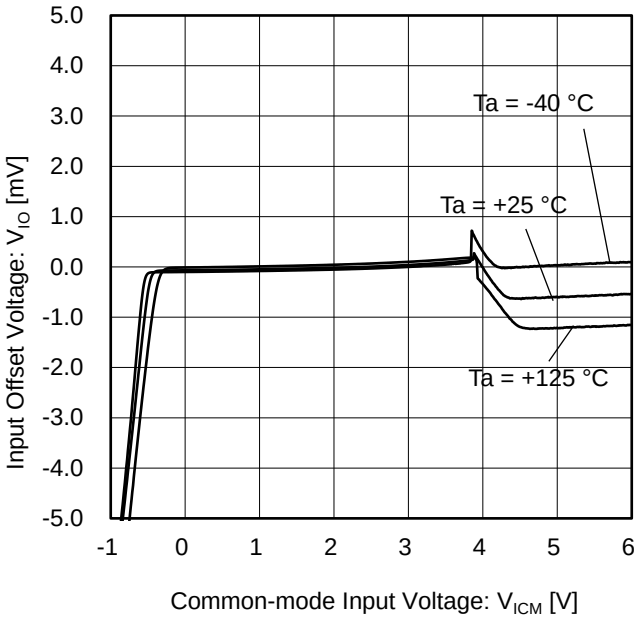

Figure 11. Input Offset Voltage vs Common-mode Input Voltage
(V_S = 5 V)

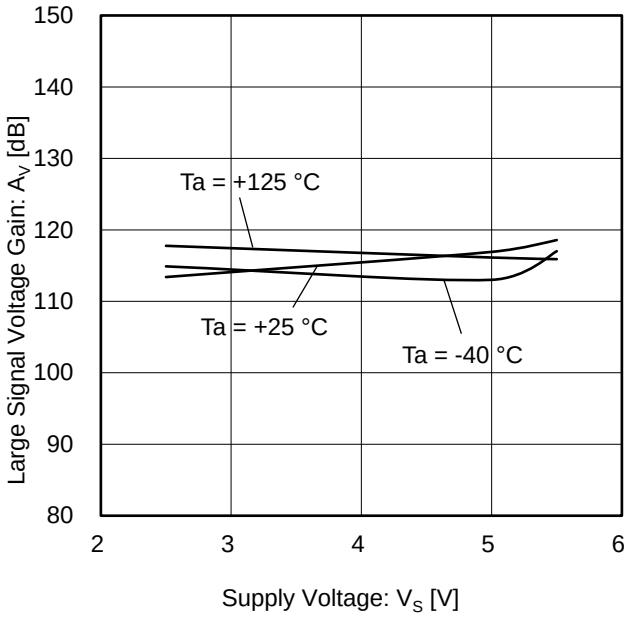

Figure 12. Large Signal Voltage Gain vs Supply Voltage
(R_L = 10 kΩ)

(Note) The above data is measurement value of typical sample, it is not guaranteed.

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Typical Performance Curves - continued
V_{SS} = 0 V

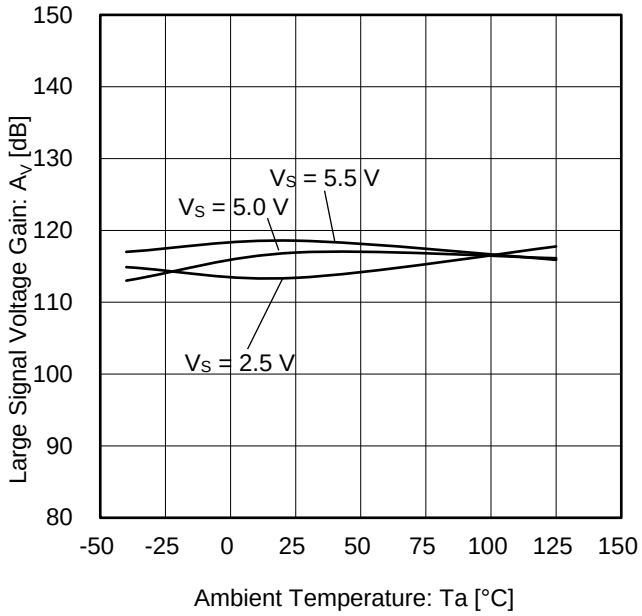

Figure 13. Large Signal Voltage Gain vs Ambient Temperature

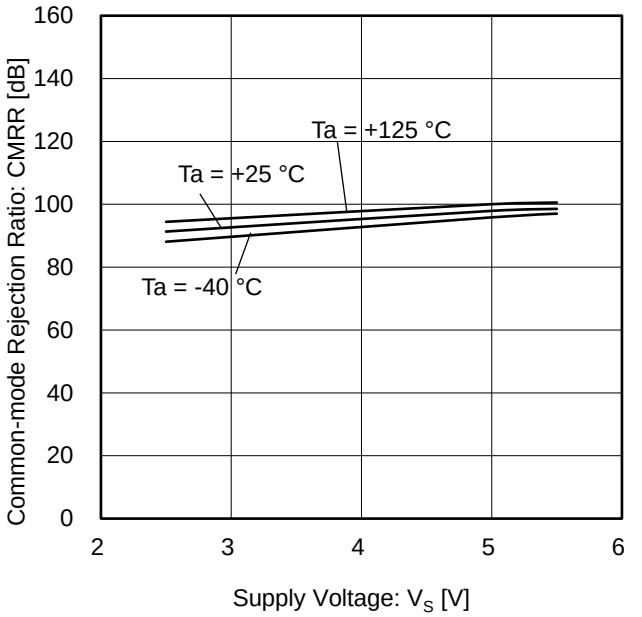

Figure 14. Common-mode Rejection Ratio vs Supply Voltage

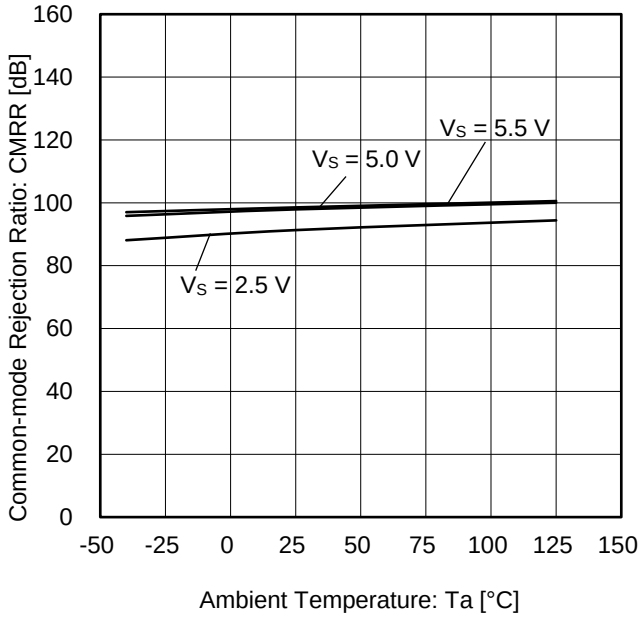

Figure 15. Common-mode Rejection Ratio vs Ambient Temperature

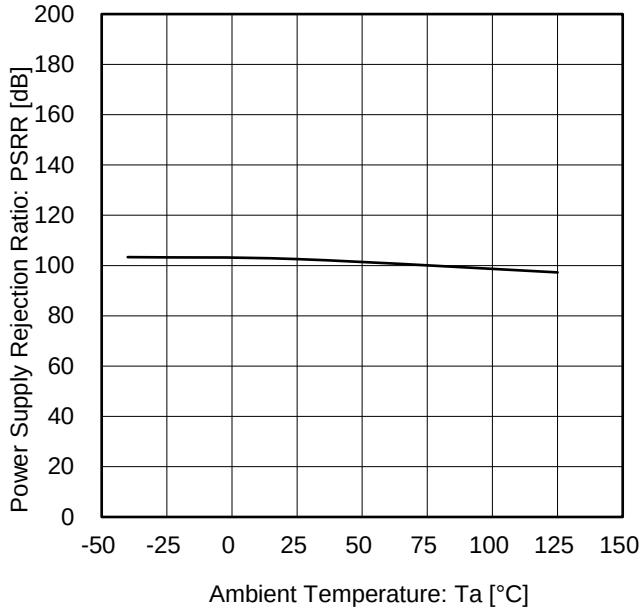

Figure 16. Power Supply Rejection Ratio vs Ambient Temperature

(Note) The above data is measurement value of typical sample, it is not guaranteed.

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Typical Performance Curves - continued
V_{SS} = 0 V

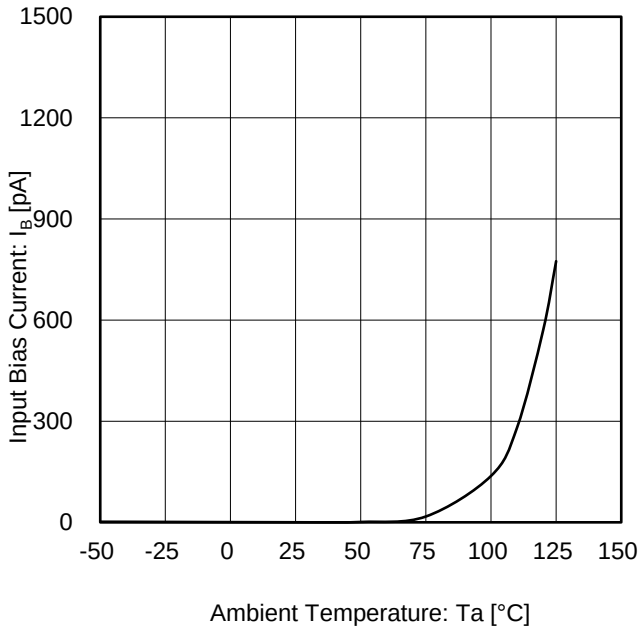

Figure 17. Input Bias Current vs Ambient Temperature
(V_S = 5 V)

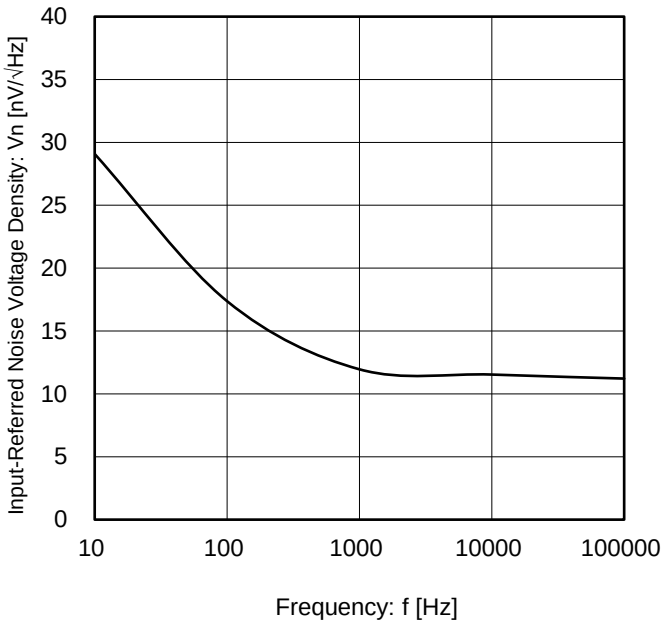

Figure 18. Input-Referred Noise Voltage Density vs Frequency
(V_S = 5 V)

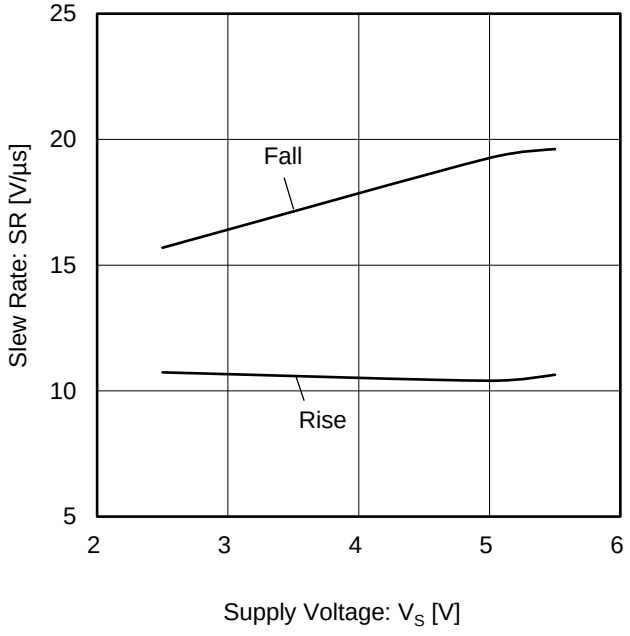

Figure 19. Slew Rate vs Supply Voltage

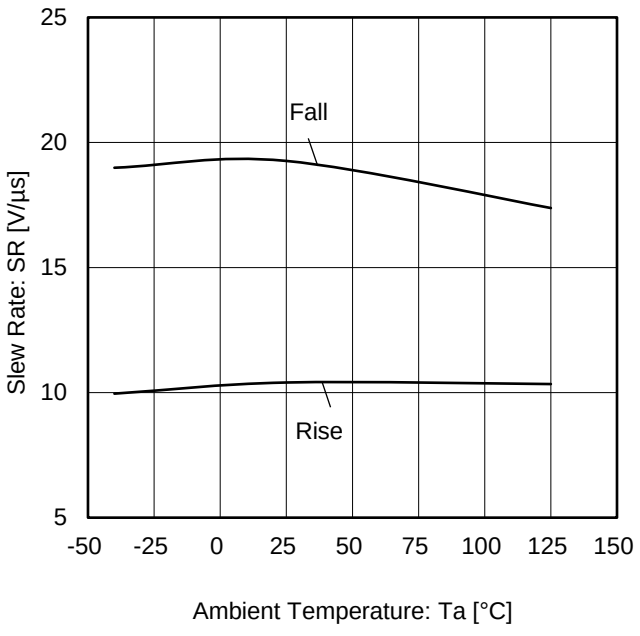

Figure 20. Slew Rate vs Ambient Temperature
(V_S = 5 V)

(Note) The above data is measurement value of typical sample, it is not guaranteed.

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Typical Performance Curves - continued
V_{SS} = 0 V

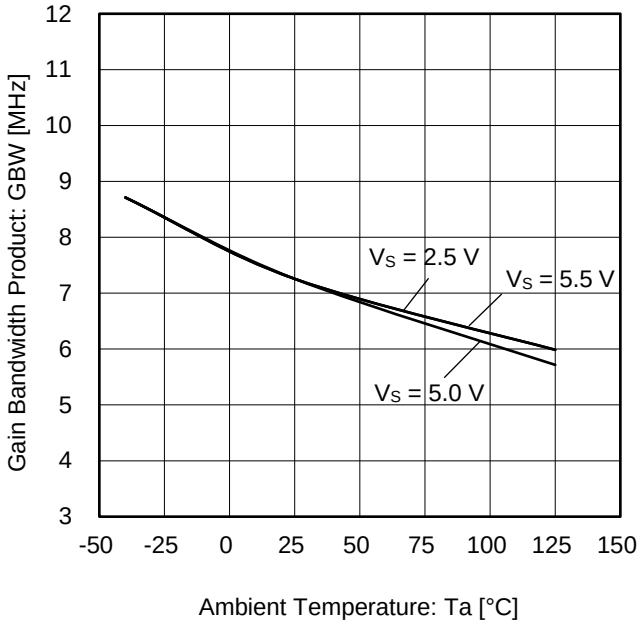

Figure 21. Gain Bandwidth Product vs Ambient Temperature

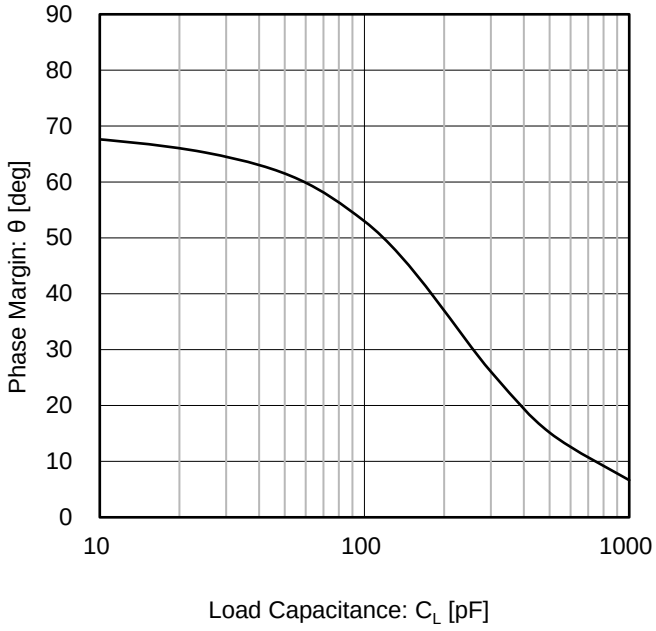

Figure 22. Phase Margin vs Load Capacitance
(V_S = 5 V, R_F = 10 kΩ, G = 40 dB)

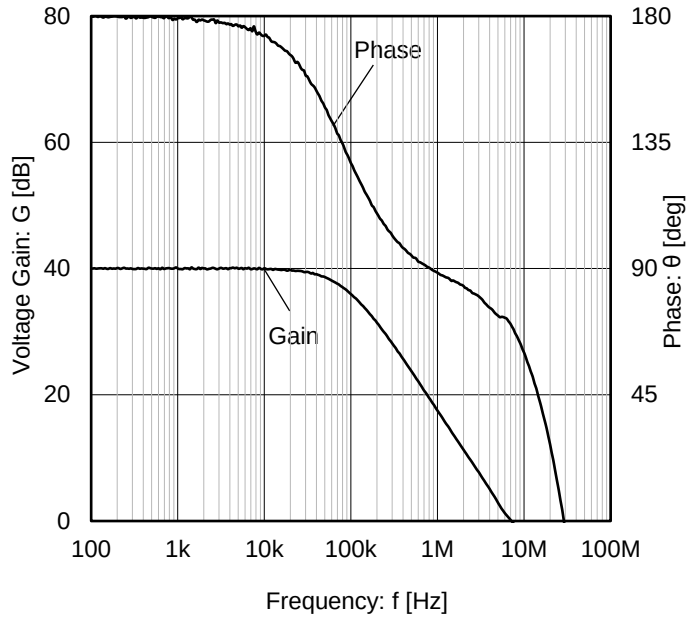

Figure 23. Voltage Gain, Phase vs Frequency
(V_S = 5 V)

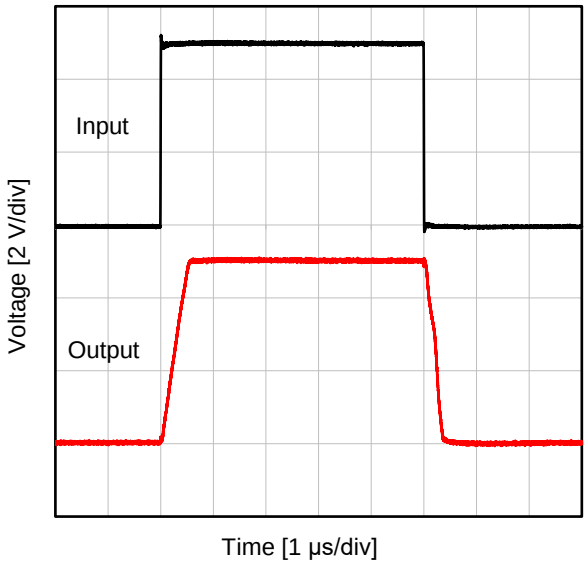

Figure 24. Large-Signal Step Response
(V_S = 5 V, G = 0 dB, R_L = 10 kΩ, C_L = 100 pF)

(Note) The above data is measurement value of typical sample, it is not guaranteed.

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Application Examples

○Voltage Follower

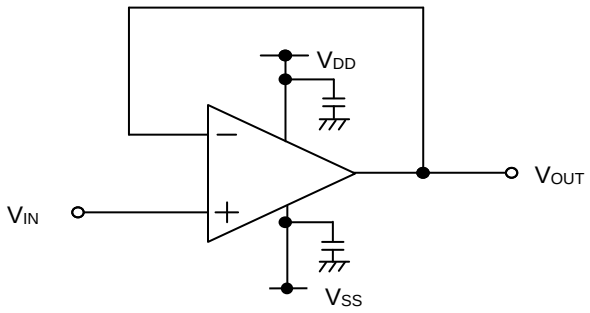

Figure 25. Voltage Follower Circuit

Using this circuit, the output voltage (V_{OUT}) is configured to be equal to the input voltage (V_{IN}). This circuit also stabilizes the output voltage due to high input impedance and low output impedance. Computation for output voltage is shown below.

$$V_{OUT} = V_{IN}$$

○Inverting Amplifier

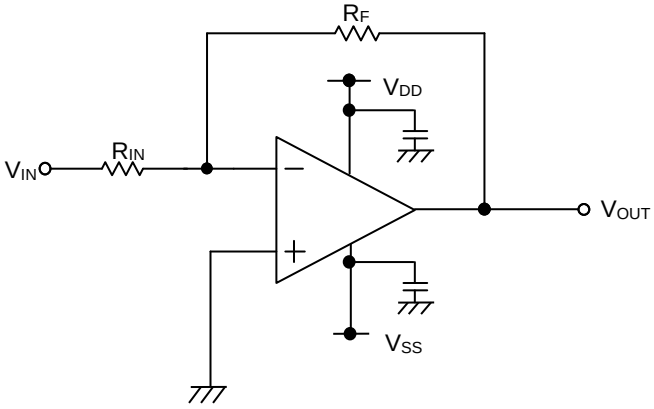

Figure 26. Inverting Amplifier Circuit

For inverting amplifier, input voltage (V_{IN}) is amplified by a voltage gain which depends on the ratio of R_{IN} and R_F, and then it outputs phase-inverted voltage. The output voltage is shown in the next expression.

$$V_{OUT} = -\frac{R_F}{R_{IN}} V_{IN}$$

This circuit has input impedance equal to R_{IN}.

○Non-inverting Amplifier

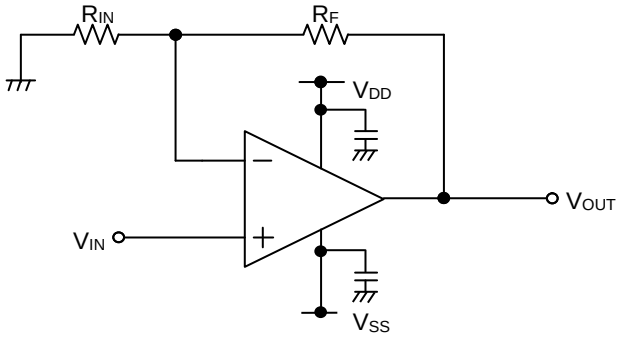

Figure 27. Non-inverting Amplifier Circuit

For non-inverting amplifier, input voltage (V_{IN}) is amplified by a voltage gain, which depends on the ratio of R_{IN} and R_F. The output voltage (V_{OUT}) is in-phase with the input voltage and is shown in the next expression.

$$V_{OUT} = \left(1 + \frac{R_F}{R_{IN}}\right) V_{IN}$$

Effectively, this circuit has high input impedance since its input side is the same as that of the operational amplifier.

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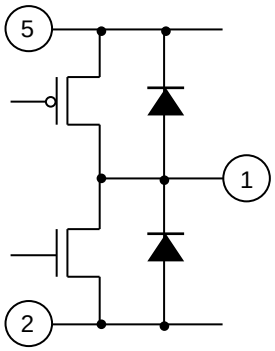
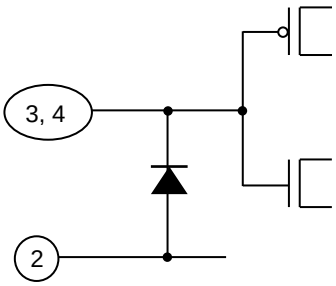
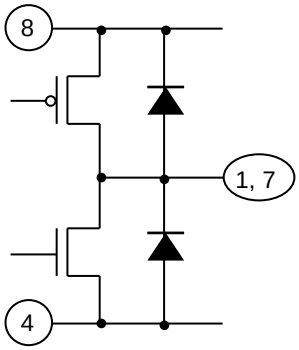
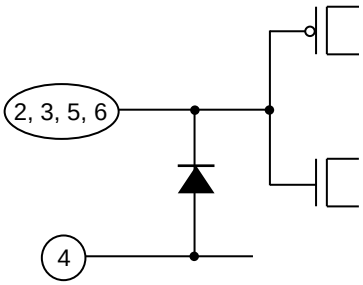
I/O Equivalence Circuits

○TLR728YG-C

Pin No.	Pin Name	Pin Description	Equivalence Circuit
1	OUT	Output	
3 4	+IN -IN	Input	

○TLR2728YFJ-C

Pin No.	Pin Name	Pin Description	Equivalence Circuit
1 7	OUT1 OUT2	Output	
2 3 5 6	-IN1 +IN1 +IN2 -IN2	Input	

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Operational Notes

1. **Reverse Connection of Power Supply**
   Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. **Power Supply Lines**
   Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. **Ground Voltage**
   Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. **Ground Wiring Pattern**
   When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. **Recommended Operating Conditions**
   The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. **Inrush Current**
   When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. **Testing on Application Boards**
   When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

8. **Inter-pin Short and Mounting Errors**
   Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

9. **Unused Input Pins**
   Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

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Operational Notes – continued

10. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

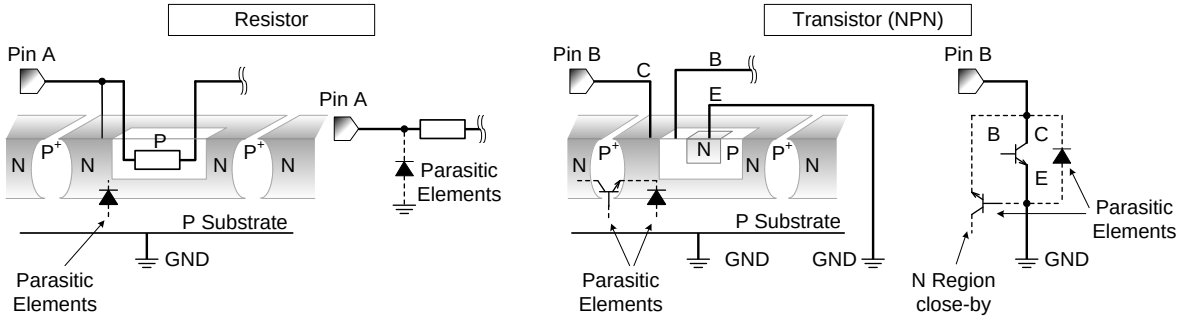

Figure 28. Example of Monolithic IC Structure

11. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

12. Functional Safety

"ISO 26262 Process Compliant to Support ASIL-*"
A product that has been developed based on an ISO 26262 design process compliant to the ASIL level described in the datasheet.
"Safety Mechanism is Implemented to Support Functional Safety (ASIL-*)"
A product that has implemented safety mechanism to meet ASIL level requirements described in the datasheet.
"Functional Safety Supportive Automotive Products"
A product that has been developed for automotive use and is capable of supporting safety analysis with regard to the functional safety.
Note: "ASIL-*" is stands for the ratings of "ASIL-A", "-B", "-C" or "-D" specified by each product's datasheet.

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Ordering Information

T	L	R	x	7	2	8	Y	x	x	-	C	x	x

Part Number
TLR728Y (Single Op-Amp)
TLR2728Y (Dual Op-Amp)

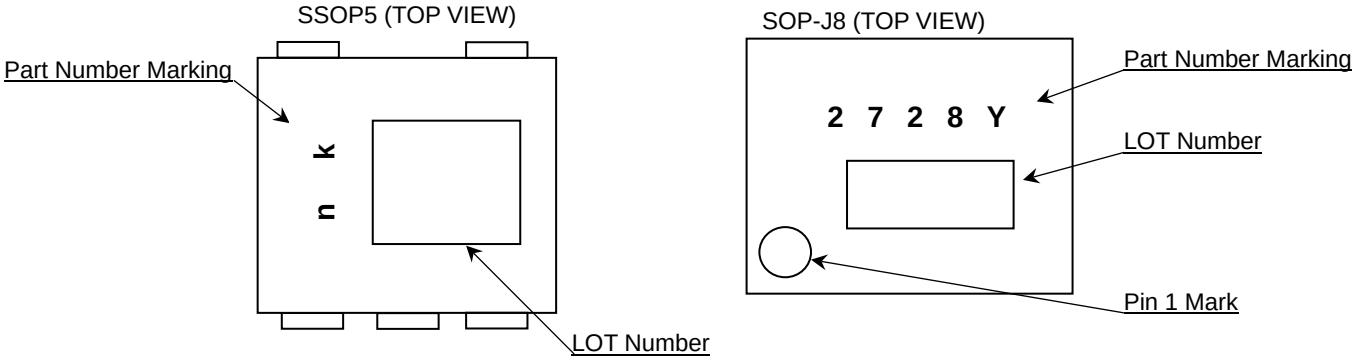
Package
G: SSOP5
FJ: SOP-J8

Product Rank
C: for Automotive applications
Packaging and forming specification
TR: Embossed tape and reel (SSOP5)
E2: Embossed tape and reel (SOP-J8)

Lineup

Number of Channels	Package		Orderable Part Number
Single	SSOP5	Reel of 3000	TLR728YG-CTR
Dual	SOP-J8	Reel of 2500	TLR2728YFJ-CE2

Marking Diagram



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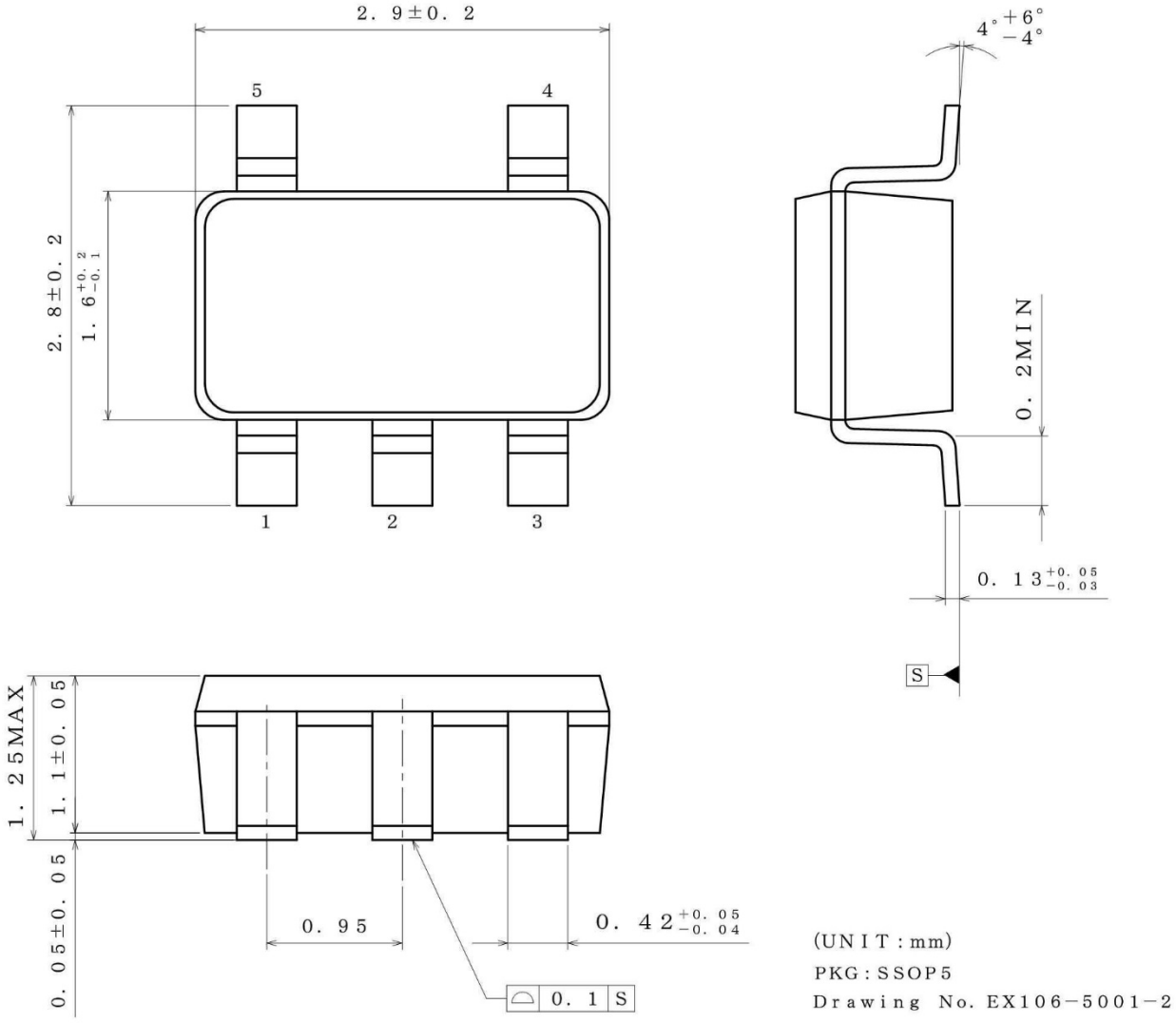
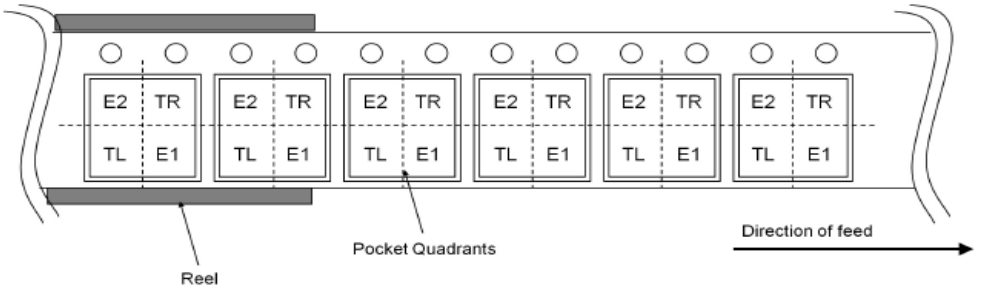
Physical Dimension and Packing Information

Package Name	SSOP5



< Tape and Reel Information >

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)



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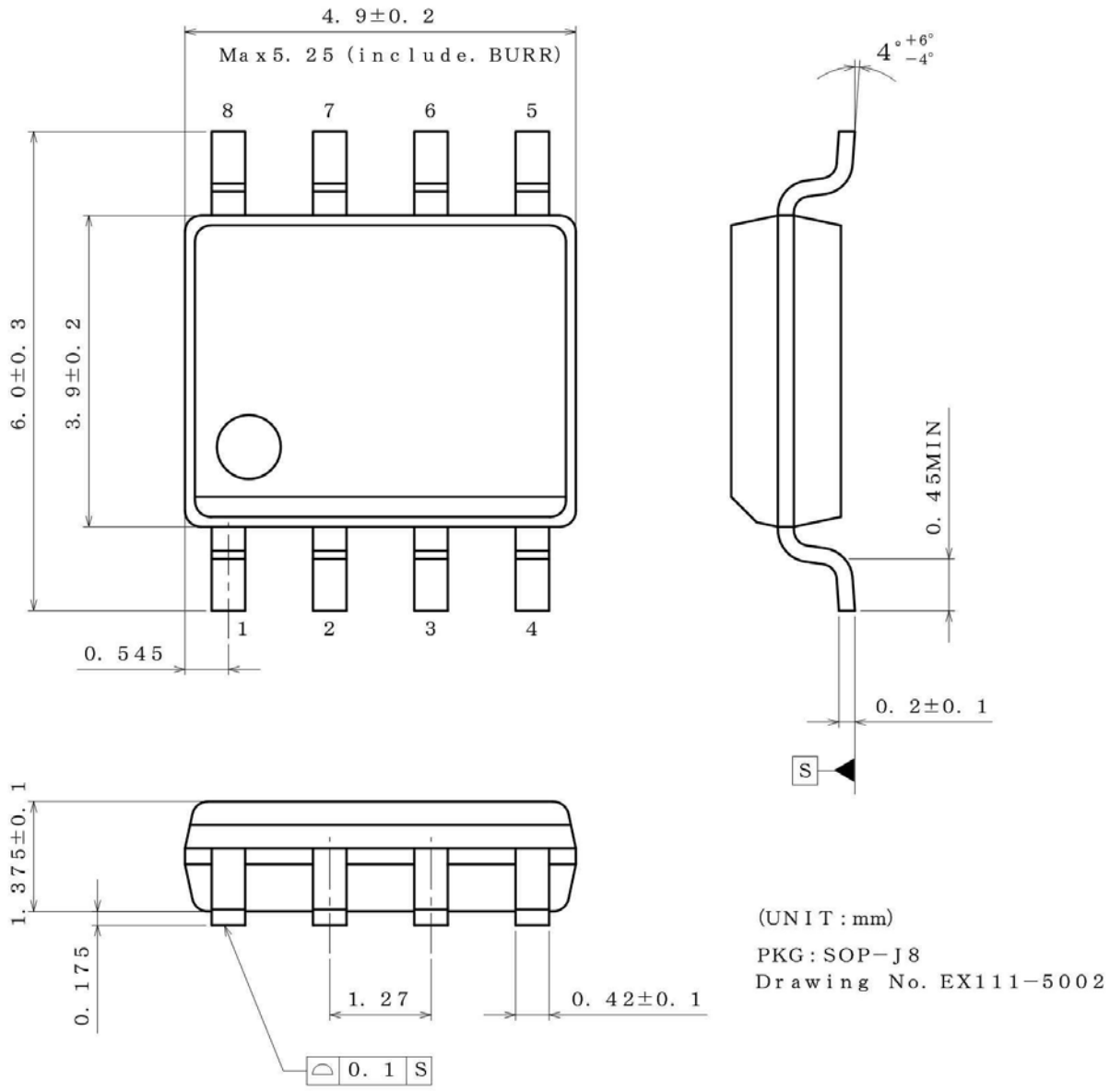
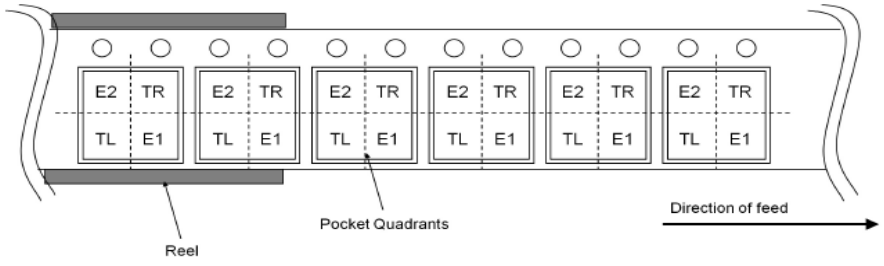
Physical Dimension and Packing Information - continued

Package Name	SOP-J8



< Tape and Reel Information >

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 The direction is the pin 1 of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand



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Revision History

Date	Revision	Changes
20.May.2025	001	New Release
10.Jul.2026	002	Add Nano Cap™ Add Lineup

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

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   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

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   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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